



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260116000.2
Qualification of additional BOM materials for select devices
Change Notification / Sample Request

Date: January 16, 2026

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260116000.2
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM3102QMH/NOPB	LM3102QMH/NOPB
LM5117QPMHE/NOPB	LM5117QPMHE/NOPB
LM5122QMHE/NOPB	LM5122QMHE/NOPB
LM26003QMH/NOPB	LM26003QMH/NOPB
LM5010AQ1MH/NOPB	LM5010AQ1MH/NOPB
LM3406HVQMHQ1	LM3406HVQMHQ1
LM5122QMH/NOPB	LM5122QMH/NOPB
LM5122QMHX/NOPB	NULL
LM5010AQ1MHX/NOPB	NULL
LM25122QPWPTQ1	LM25122QPWPTQ1
LM3423Q1MHX/NOPB	LM3423Q1MHX/NOPB
LM5575QMHX/NOPB	NULL
LM25576QMHX/NOPB	926-LM25576QMHX/NOPB
LM5575QMH/NOPB	LM5575QMH/NOPB
LM20143QMH/NOPB	LM20143QMH/NOPB
LM48100QMHE/NOPB	LM48100QMHE/NOPB
LM5161QPWPRQ1	NULL
LM25118Q1MH/NOPB	NULL
LM5161QPWPTQ1	NULL
LM5160QPWPRQ1	LM5160QPWPRQ1
LM25118Q1MHE/NOPB	LM25118Q1MHE/NOPB
LM5117QPMH/NOPB	LM5117QPMH/NOPB
LM5118Q1MHX/NOPB	LM5118Q1MHX/NOPB
LM5121QMHE/NOPB	NULL
LM25122QPWPRQ1	NULL
LM26003QMHX/NOPB	926-LM26003QMHX/NOPB
LM5160QPWPTQ1	LM5160QPWPTQ1
LM3492QMH/NOPB	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260116000.2			PCN Date:	January 16, 2026												
Title:	Qualification of additional BOM materials for select devices																
Customer Contact:	Change Management team		Dept:	Quality Services													
Proposed 1st Ship Date:	July 15, 2026		Sample requests accepted until:	March 17, 2026													
*Sample requests received after March 17, 2026 will not be supported.																	
Change Type:																	
<input type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material															
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process															
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site															
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material															
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process															
PCN Details																	
Description of Change:																	
This PCN is to inform of the qualification of additional BOM options for the devices in the product affected section as follows. Devices will remain at current Assembly sites.																	
Group 1 device (14/16PWP)																	
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Additional</th> </tr> </thead> <tbody> <tr> <td>Wire diam/type</td> <td>1.3mil Au</td> <td>1.3mil Cu</td> </tr> <tr> <td>Mount Compound</td> <td>8075531</td> <td>4211470</td> </tr> <tr> <td>Mold Compound</td> <td>8095181</td> <td>4228573</td> </tr> </tbody> </table>							Current	Additional	Wire diam/type	1.3mil Au	1.3mil Cu	Mount Compound	8075531	4211470	Mold Compound	8095181	4228573
	Current	Additional															
Wire diam/type	1.3mil Au	1.3mil Cu															
Mount Compound	8075531	4211470															
Mold Compound	8095181	4228573															
Group 2 device (20/28PWP)																	
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	Current	Additional															
Wire diam/type	1.0mil Au	1.0mil Cu															
Mount Compound	8075531	4211470															
Mold Compound	8095181	4228573															
Reason for Change:																	
Continuity of supply																	
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																	
None																	
Impact on Environmental Ratings:																	
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.																	
<table border="1"> <thead> <tr> <th>RoHS</th> <th>REACH</th> <th>Green Status</th> <th>IEC 62474</th> </tr> </thead> <tbody> <tr> <td><input checked="" type="checkbox"/> No Change</td> </tr> </tbody> </table>						RoHS	REACH	Green Status	IEC 62474	<input checked="" type="checkbox"/> No Change							
RoHS	REACH	Green Status	IEC 62474														
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change														
Changes to product identification resulting from this PCN:																	
None																	
Group 1 Product Affected:																	
LM20123QMH/NOPB		LM20154QMH/NOPB		LM3429Q1MHX/NOPB													

LM20123QMHE/NOPB	LM20154QMHE/NOPB	LM48100QMH/NOPB
LM20123QMHX/NOPB	LM20154QMHX/NOPB	LM48100QMHE/NOPB
LM20124QMH/NOPB	LM25010Q1MH/NOPB	LM48100QMHX/NOPB
LM20124QMHE/NOPB	LM25010Q1MHX/NOPB	LM5010AQ1MH/NOPB
LM20124QMHX/NOPB	LM25088QMH-1/NOPB	LM5010AQ1MHX/NOPB
LM20125QMH/NOPB	LM25088QMH-2/NOPB	LM5088QMH-1/NOPB
LM20125QMHE/NOPB	LM25088QMHX-1/NOPB	LM5088QMH-2/NOPB
LM20125QMHX/NOPB	LM25088QMHX-2/NOPB	LM5088QMHX-1/NOPB
LM20133QMH/NOPB	LM25575QMH/NOPB	LM5088QMHX-2/NOPB
LM20133QMHE/NOPB	LM25575QMHX/NOPB	LM5160QPWPQ1
LM20133QMHX/NOPB	LM26001QMXA/NOPB	LM5160QPWPRQ1
LM20134QMHE/NOPB	LM26001QMXAX/E7002781	LM5160QPWPPTQ1
LM20134QMHX/NOPB	LM26001QMXAX/J7002617	LM5161QPWPRQ1
LM20143QMH/NOPB	LM26001QMXAX/J7002755	LM5161QPWPPTQ1
LM20143QMHE/NOPB	LM26001QMXAX/NOPB	LM5575QMH/NOPB
LM20143QMHX/NOPB	LM3406HVQMHQ1	LM5575QMHX/NOPB
LM20144QMHE/NOPB	LM3406HVQMHXQ1	TPS92690Q1PWP/NOPB
LM20144QMHX/NOPB	LM3421Q1MH/NOPB	TPS92690Q1PWPR/NOPB
LM20145QMHE/NOPB	LM3421Q1MHX/NOPB	
LM20145QMHX/NOPB	LM3429Q1MH/NOPB	

Group 2 Product Affected:

EMB1499QMH/NOPB	LM3423Q1MHX/NOPB	LM5118Q1MHX/NOPB
EMB1499QMHE/NOPB	LM3423Q1MHX/S7002462	LM5121QMH/NOPB
EMB1499QMHX/NOPB	LM3424QMH/NOPB	LM5121QMHE/NOPB
LM25117QPMH/NOPB	LM3424QMHX/NOPB	LM5121QMHX/NOPB
LM25117QPMHE/NOPB	LM3431AQMH/NOPB	LM5122QMH/NOPB
LM25117QPMHX/NOPB	LM3431AQMHX/NOPB	LM5122QMHE/NOPB
LM25118Q1MH/NOPB	LM3431QMH/NOPB	LM5122QMHX/NOPB
LM25118Q1MHE/NOPB	LM3431QMHX/NOPB	LM5122QPWPRA
LM25118Q1MHX/NOPB	LM3492EHCQMH	LM5122QPWPPTA
LM25122QPWPRQ1	LM3492EHCQMHX	LM5576QMH/NOPB
LM25122QPWPPTQ1	LM3492HCQMH/NOPB	LM5576QMHX/NOPB
LM25576QMH/NOPB	LM3492HCQMHX/NOPB	TDC1000QPWQ1
LM25576QMHX/NOPB	LM3492QMH/NOPB	TDC1000QPWRQ1
LM26003QMH/NOPB	LM3492QMHX/NOPB	TDC1011QPWQ1
LM26003QMHE/E7002413	LM34937QPMH/NOPB	TDC1011QPWRQ1
LM26003QMHX/NOPB	LM34937QPMHX/NOPB	
LM3102QMH/NOPB	LM5117QPMH/NOPB	
LM3102QMHX/NOPB	LM5117QPMHE/NOPB	
LM3423Q1MH/NOPB	LM5117QPMHX/NOPB	
LM3423Q1MH/S7002461	LM5118Q1MH/NOPB	

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)
 Approve Date 07-October-2025

Product Attributes

Attributes		Qual Device: LM20123QMHE/NOPB	Qual Device: LM5161QPWPRQ1	Qual Device: LM5118Q1MH/NOPB	QBS Package Reference: LM5576QMH/NOPB
Automotive Grade Level		Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function		ASIC, Microprocessor	Logic	Logic	Power Management
Wafer Fab Supplier		MAINEFAB	MAINEFAB	MAINEFAB	RFAB
Assembly Site		TIEMA	TIEMA	TIEMA	TIEMA
Package Group		TSSOP	TSSOP	TSSOP	TSSOP
Package Designator		PWP	PWP	PWP	PWP
Pin Count		16	14	20	20

QBS: Qual By Similarity, also known as Generic Data

Qual Device LM20123QMHE/NOPB is qualified at MSL1 260C

Qual Device LM5161QPWPRQ1 is qualified at MSL3 260C

Qual Device LM5118Q1MH/NOPB is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: LM20123QMHE/NOPB	Qual Device: LM5161QPWPRQ1	Qual Device: LM5118Q1MH/NOPB	QBS Package Reference: LM5576QMH/NOPB
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	3/231/0	-	3/693/0	3/693/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	3/462/0	-	-
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
TC-SAM	A4	-	3	3	Post TC SAM	<50% delamination	-	3/36/0	3/36/0	3/36/0	3/36/0
TC-WBP	A4	MIL-STD883 Method 2011	3	30	Bond Pull over Ball Post T/C 500 Cycles	-	Wires	3/90/0	3/90/0	3/90/0	3/90/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	3/231/0	1/77/0
Test Group C - Package Assembly Integrity Tests											

WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	-	-	1/30/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	3/30/0	-	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements			
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements			
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements			
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements			
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements			
Test Group E - Electrical Verification Tests											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-	-	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-	-	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	-	-	1/3/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	3/90/0	3/90/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-043

Qualification Report

Automotive Qualification Summary

(As per AEC and JEDEC Guidelines)

Q006 TSSOP at TIEM
Approve Date 06-October-2025

Product Attributes

Attributes		Qual Device: <u>LM20123QMHE/NOPB</u>	Qual Device: <u>LM5161QPWPRQ1</u>	Qual Device: <u>LM5118Q1MH/NOPB</u>	QBS Package Reference: <u>LM5576QMH/NOPB</u>
Automotive Grade Level		Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)		-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function		ASIC, Microprocessor	Logic	Logic	Power Management
Wafer Fab Supplier		MAINEFAB	MAINEFAB	MAINEFAB	RFAB
Assembly Site		TIEMA	TIEMA	TIEMA	TIEMA
Package Group		TSSOP	TSSOP	TSSOP	TSSOP
Package Designator		PWP	PWP	PWP	PWP
Pin Count		16	14	20	20

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>LM20123QMHE/NOPB</u>	Qual Device: <u>LM5161QPWPRQ1</u>	Qual Device: <u>LM5118Q1MH/NOPB</u>	QBS Reference: <u>LM5576QMH/NOPB</u>
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	3/231/0	-	3/693/0	3/693/0
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	-	3/462/0	-	-
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	3/66/0	3/66/0	3/66/0	3/66/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	3/66/0	3/66/0	3/66/0	3/66/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	3/231/0	3/231/0
HAST	A2.1.2	-	3	1	Cross Section, post bHAST, 1X	Post stress cross section	Completed	-	-	3/3/0	3/3/0
HAST	A2.1.3	-	3	3	Wire Bond Shear, post bHAST, 1X	Post stress	-	-	-	3/9/0	3/9/0
HAST	A2.1.4	-	3	3	Bond Pull over Stitch, post bHAST, 1X	Post stress	-	-	-	3/9/0	3/9/0
HAST	A2.1.5	-	3	3	Bond Pull over Ball, post bHAST, 1X	Post stress	-	-	-	3/9/0	3/9/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	-	-	3/231/0	3/231/0
HAST	A2.2.1	-	3	22	SAM Analysis, post bHAST 2X	Review for delamination	Completed	-	-	3/66/0	3/66/0
HAST	A2.2.2	-	3	1	Cross Section, post bHAST, 2X	Post stress cross section	Completed	-	-	3/3/0	3/3/0
HAST	A2.2.3	-	3	3	Wire Bond Shear, post bHAST, 2X	Post stress	-	-	-	3/9/0	3/9/0
HAST	A2.2.4	-	3	3	Bond Pull over Stitch, post bHAST, 2X	Post stress	-	-	-	3/9/0	3/9/0

HAST	A2.2.5	-	3	3	Bond Pull over Ball, post bHAST, 2X	Post stress	-	-	-	3/9/0	3/9/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	3/66/0	3/66/0	3/66/0	3/66/0
TC	A4.1.2	-	3	1	Cross Section, post TC, 1X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0	3/3/0
TC	A4.1.3	-	3	3	Wire Bond Shear, post TC, 1X	Post stress	-	3/9/0	3/9/0	3/9/0	3/9/0
TC	A4.1.4	-	3	3	Bond Pull over Stitch, post TC, 1X	Post stress	-	3/9/0	3/9/0	3/9/0	3/9/0
TC	A4.1.5	-	3	3	Bond Pull over Ball, post TC, 1X	Post stress	-	3/9/0	3/9/0	3/9/0	3/9/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	3/231/0	3/231/0	3/231/0	3/231/0
TC	A4.2.1	-	3	22	SAM Analysis, post TC, 2X	Review for delamination	Completed	3/66/0	3/66/0	3/66/0	3/66/0
TC	A4.2.2	-	3	1	Cross Section, post TC, 2X	Post stress cross section	Completed	3/3/0	3/3/0	3/3/0	3/3/0
TC	A4.2.3	-	3	3	Wire Bond Shear, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0	3/9/0
TC	A4.2.4	-	3	3	Bond Pull over Stitch, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0	3/9/0
TC	A4.2.5	-	3	3	Bond Pull over Ball, post TC, 2X	Post stress	-	3/9/0	3/9/0	3/9/0	3/9/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	1000 Hours	-	3/135/0	3/135/0	3/135/0
HTSL	A6.1.1	-	3	1	Cross Section, post HTSL, 1X	Post stress cross section	Completed	-	3/3/0	3/3/0	3/3/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	2000 Hours	-	3/135/0	3/135/0	3/135/0
HTSL	A6.2.1	-	3	1	Cross Section, post HTSL, 2X	Post stress cross section	Completed	-	3/3/0	3/3/0	3/3/0
Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	3/90/0	3/90/0	3/90/0	3/90/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device LM20123QMHE/NOPB is qualified at MSL1 260C

Qual Device LM5161QPWPRQ1 is qualified at MSL3 260C

Qual Device LM5118Q1MH/NOPB is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2403-043

ZVEI ID: SEM-PA-07, SEM-PA-08, SEM-PA-11

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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